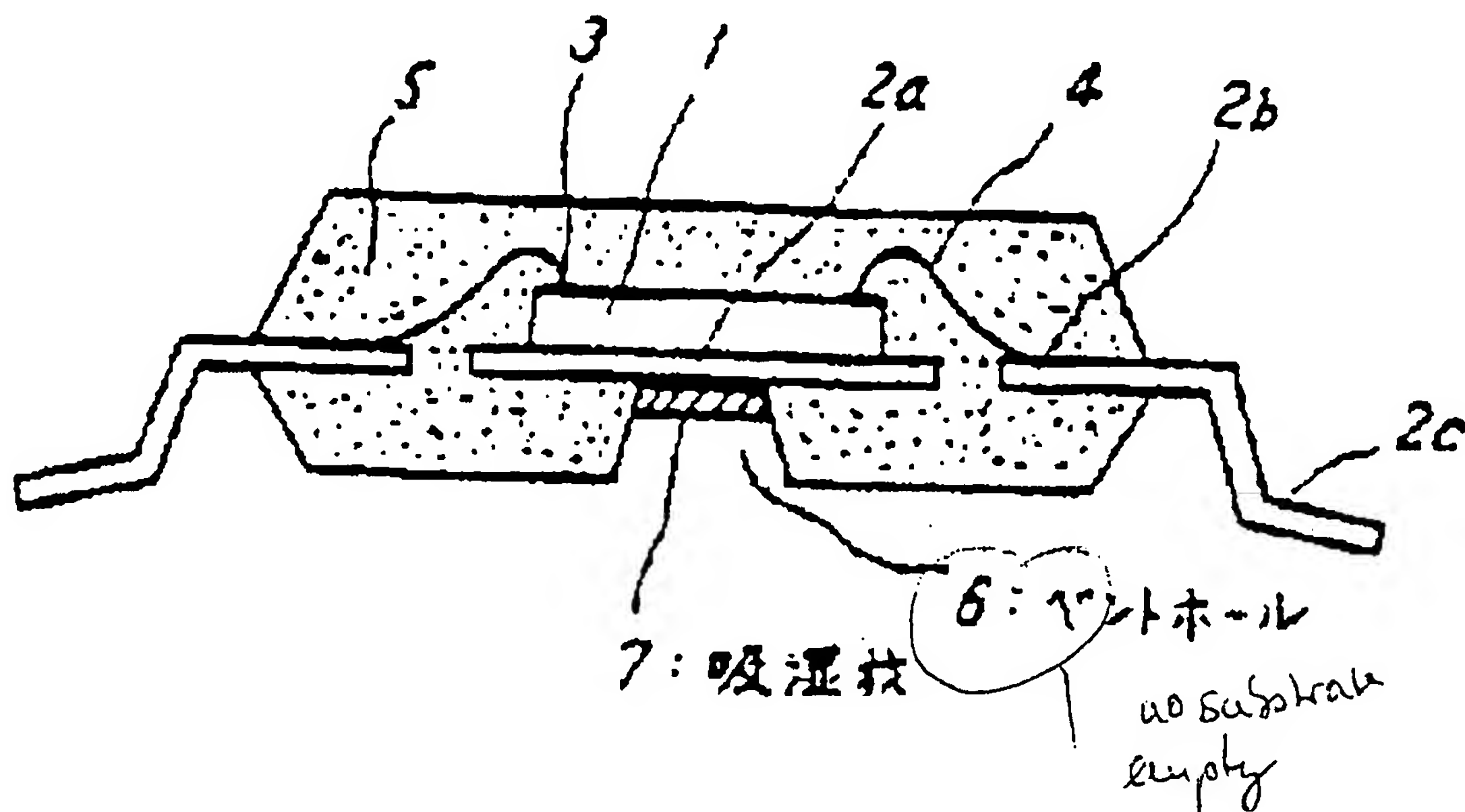


AN: PAT 1992-036845
TI: Resin encapsulated semiconductor device with vent hole has moisture absorbing material having higher absorption capacity than resin and coloured by absorption adhered at die pad exposed by hole
PN: JP03283453-A
PD: 13.12.1991
AB: The composite magnet comprises cylindrical outer shell consisting of metal having sufficient strength and maleability, in which metallic materials exist. At least one of the metallic materials comprises metallic permanent magnet material modified into filled-up material by plasticising powder material. The materials are closely attached to each other at the interfaces which are parallel to the centre axis line of the cylindrical shell. In a cylindrical capsule consisting of metal having sufficient strength and maleability, partitions consisting of the filled-up metal, which have surfaces parallel to the centre axis line of the capsule, are inserted. In at least one of the other spaces, permanent magnet metal powder material is filled, and in the rest, appropriate metal powder or filling metal material is admitted. The capsule is closed, and hot or warm extrusion is applied.; The composite magnet is used for the magnetic sensor. The magnet is easily welded, soldered, or processed with machines. Vibration resistance and shock resistance of the magnet are improved.
PA: (OKID) OKI ELECTRIC IND CO LTD;
FA: JP03283453-A 13.12.1991;
CO: JP;
IC: H01L-023/29;
MC: A12-E04; A12-E07C; L04-C20A; U11-D01A3; U11-D01C9; U11-E02A;
DC: A85; L03; U11;
FN: 1992036845.gif
PR: JP0081036 30.03.1990;
FP: 13.12.1991
UP: 27.01.1992

BGA Hitachi

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本発明の樹脂封止型半導体装置の断面図

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